

CLAIMS

1. A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, and blowing means installed in said chambers, wherein the centers of the impellers in said adjacent blowing means are not on a single perpendicular plane along a transport line of said conveyor and arrayed offset to the left and right.
2. A reflow soldering apparatus as claimed in claim 1, wherein said blowing means are arrayed left and right in a zigzag pattern along the transport line of said conveyor.
3. A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, and blowing means installed in said chambers, wherein the centers of the impellers in said adjacent blowing means are not on a single horizontal plane and arrayed offset up and down.
4. A reflow soldering apparatus as claimed in claim 3, wherein said blowing means are arrayed above and below in a zigzag pattern along the transport line of said conveyor.
5. A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, and blowing means installed in said

chambers, wherein said blowing means are arranged with their rotating shafts inclined in said chambers.

6. A reflow soldering apparatus as claimed in claim 5, wherein said blowing means are installed above and below said conveyor, and the rotating shafts of said upper and lower blowing means are arranged diagonally in different directions.

7. A reflow soldering apparatus as claimed in claim 5, wherein said blowing means are installed above and below said conveyor, and the rotating shafts of said upper and lower blowing means are arranged diagonally in the same direction.